



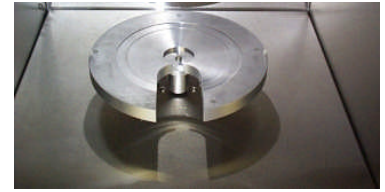
Applied Physics, Inc.

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Monte Vista, CO 81144 USA

Nano Particle Technology

Cel 1-720-635-3931
Email Sales@AppliedPhysicsUSA.com
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Particle Deposition System, PDS-300



Full Deposition Wafer Platen



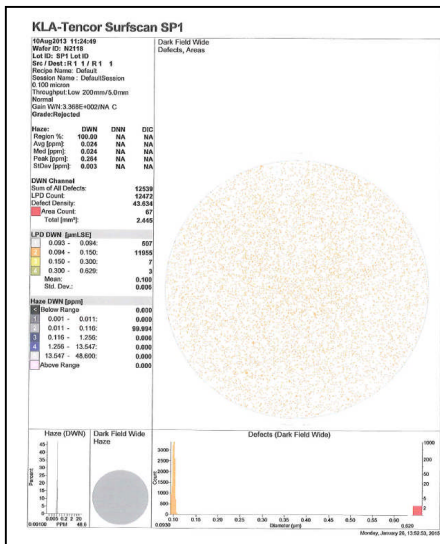
Deposition Timer Control

Particle Deposition System, PDS-300 w/ Optional Half Deposition, Platen Control

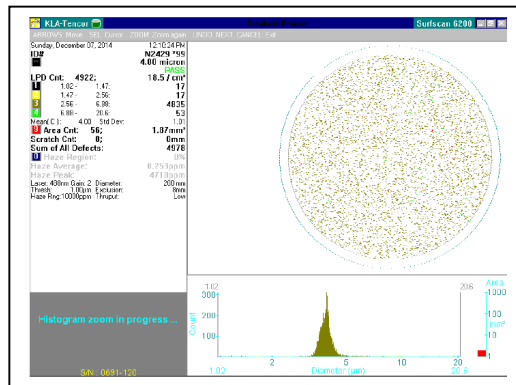
The Particle Deposition System, PDS-300 is designed to produce PSL Wafer Standards and SiO₂ Particle Wafer Standards on 300mm, 200mm, 150mm, 125mm and 100mm silicon wafers, or FILM wafers, depositing the PSL (polystyrene latex) or SiO₂ Particle peak size on the wafer surface, FILM surface or pattern wafer. The PDS-300 controls the particle deposition through constant airflow and exhaust, timing and type of deposition, i.e.; full deposition, half deposition or spot deposition. Deposition Count is controlled by a timed deposition from 10 seconds to 1 minute or more with most depositions from 60nm to 5 microns, depending on the PSL or SiO₂ concentration in DI Water suspended in the glass nebulizer.

Low Cost, NIST Traceable, 100mm to 300mm PSL Wafer Standards & Particle Wafer Standards, 60nm to 5um
Prime Silicon Wafers, Film Wafers, Patterned Wafers, Blank Photo Masks

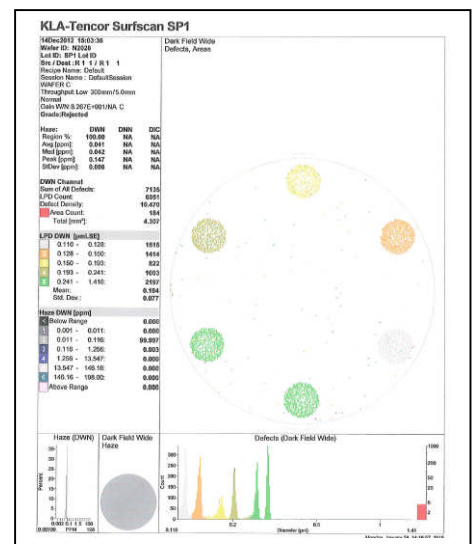
PDS-300 Depositions and Wafer Scan Results using KLA-Tencor SP1 and Tencor 6200 Wafer Inspection Systems



200mm, FULL DEP: 0.102um



150mm, KLA-Tencor 6200 Scan, 4um, FULL DEP



300mm, SPOT DEP: 125nm, 147nm, 204nm, 304nm, 350nm

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